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Contact us

Tel: +86-755-8981 8866 Fax: +86-755-8427 6832

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September 1983 Revised May 2005

MM74HC244 Octal 3-STATE Buffer

General Description

The MM74HC244 is a non-inverting buffer and has two active low enables (1G and 2G); each enable independently controls 4 buffers. This device does not have Schmitt trigger inputs.

These 3-STATE buffers utilize advanced silicon-gate CMOS technology and are general purpose high speed non-inverting buffers. They possess high drive current outputs which enable high speed operation even when driving large bus capacitances. These circuits achieve speeds comparable to low power Schottky devices, while retaining the advantage of CMOS circuitry, i.e., high noise immunity, and low power consumption. All three devices have a fanout of 15 LS-TTL equivalent inputs.

All inputs are protected from damage due to static discharge by diodes to $\mbox{V}_{\mbox{\scriptsize CC}}$ and ground.

Features

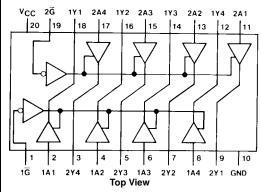
- Typical propagation delay: 14 ns
- 3-STATE outputs for connection to system buses
- Wide power supply range: 2-6V
- Low quiescent supply current: 80 µA
- Output current: 6 mA

Ordering Code:

Order Number	Package Number	Package Description
MM74HC244WM	M20B	20-Lead Small Outline Integrated Circuit (SOIC), JEDEC MS-013, 0.300" Wide
MM74HC244SJ	M20D	20-Lead Small Outline Package (SOP), EIAJ TYPE II, 5.3mm Wide
MM74HC244MTC	MTC20	20-Lead Thin Shrink Small Outline Package (TSSOP), JEDEC MO-153, 4.4mm Wide
MM74HC244N	N20A	20-Lead Plastic Dual-In-Line Package (PDIP), JEDEC MS-001, 0.300" Wide

Devices also available in Tape and Reel. Specify by appending the suffix letter "X" to the ordering code

Connection Diagram



Truth Table

1G	1A	1Y	2G	2A	2Y
L	L	L	L	L	L
L	Н	Н	L	Н	Н
Н	L	Z	Н	L	Z
Н	Н	Z	Н	Н	Z

- H = HIGH Level
- L = LOW Level Z = High Impedance

Absolute Maximum Ratings(Note 1)

(Note 2)

Supply Voltage (V _{CC})	-0.5 to +7.0V
DC Input Voltage (V _{IN})	-1.5 to $V_{CC} + 1.5V$
DC Output Voltage (V _{OUT})	-0.5 to V_{CC} $+0.5V$
Clamp Diode Current (I _{IK} , I _{OK})	± 20 mA
DC Output Current, per pin (I _{OUT})	± 35 mA
DC V_{CC} or GND Current, per pin (I_{CC})	± 70 mA
Storage Temperature Range (T _{STG})	-65°C to +150°C
Power Dissipation (P _D)	
(Note 3)	600 mW
S.O. Package only	500 mW
Lead Temperature (T _L)	

Recommended Operating Conditions

	Min	Max	Units
Supply Voltage (V _{CC})	2	6	V
DC Input or Output Voltage			
(V_{IN}, V_{OUT})	0	V_{CC}	V
Operating Temperature Range (T _A)	-40	+85	°C
Input Rise or Fall Times			
$(t_r, t_f) V_{CC} = 2.0V$		1000	ns
V _{CC} = 4.5V		500	ns
$V_{CC} = 6.0V$		400	ns

Note 1: Absolute Maximum Ratings are those values beyond which damage to the device may occur.

Note 2: Unless otherwise specified all voltages are referenced to ground.

Note 3: Power Dissipation temperature derating — plastic "N" package: – 12 mW/°C from 65°C to 85°C.

DC Electrical Characteristics (Note 4)

(Soldering 10 seconds)

Symbol	Parameter	Conditions	v _{cc}	T _A = 25°C		T _A = -40 to 85°C	T _A = -55 to 125°C	Units
Symbol				Тур		Guaranteed L	imits	Units
V _{IH}	Minimum HIGH Level		2.0V		1.5	1.5	1.5	V
	Input Voltage		4.5V		3.15	3.15	3.15	V
			6.0V		4.2	4.2	4.2	V
V _{IL}	Maximum LOW Level		2.0V		0.5	0.5	0.5	V
	Input Voltage		4.5V		1.35	1.35	1.35	V
			6.0V		1.8	1.8	1.8	V
V _{OH}	Minimum HIGH Level	$V_{IN} = V_{IH}$ or V_{IL}						
	Output Voltage	$ I_{OUT} \leq 20 \; \mu A$	2.0V	2.0	1.9	1.9	1.9	V
			4.5V	4.5	4.4	4.4	4.4	V
			6.0V	6.0	5.9	5.9	5.9	V
		$V_{IN} = V_{IH}$ or V_{IL}						V
		$ I_{OUT} \leq 6.0 \; mA$	4.5V	4.2	3.98	3.84	3.7	V
		$ I_{OUT} \leq 7.8 \; mA$	6.0V	5.7	5.4	5.34	5.2	V
V _{OL}	Maximum LOW Level	$V_{IN} = V_{IH}$ or V_{IL}						
	Output Voltage	$ I_{OUT} \leq 20 \; \mu A$	2.0V	0	0.1	0.1	0.1	V
			4.5V	0	0.1	0.1	0.1	V
			6.0V	0	0.1	0.1	0.1	V
		$V_{IN} = V_{IH}$ or V_{IL}						
		$ I_{OUT} \le 6.0 \text{ mA}$	4.5V	0.2	0.26	0.33	0.4	V
		$ I_{OUT} \leq 7.8 \; mA$	6.0V	0.2	0.26	0.33	0.4	V
I _{IN}	Maximum Input	V _{IN} = V _{CC} or GND	6.0V		± 0.1	± 1.0	±1.0	μА
	Current							
loz	Maximum 3-STATE	$V_{IN} = V_{IH}$, or V_{IL}	6.0V		± 0.5	± 5	±10	μΑ
	Output Leakage	$V_{OUT} = V_{CC}$ or GND						
	Current	$\overline{G} = V_{IH}$						
I _{CC}	Maximum Quiescent	V _{IN} = V _{CC} or GND	6.0V		8.0	80	160	μΑ
	Supply Current	$I_{OUT} = 0 \mu A$						

260°C

Note 4: For a power supply of 5V ± 10% the worst case output voltages (V_{OH}, and V_{OL}) occur for HC at 4.5V. Thus the 4.5V values should be used when designing with this supply. Worst case V_{IH} and V_{IL} occur at V_{CC} = 5.5V and 4.5V respectively. (The V_{IH} value at 5.5V is 3.85V.) The worst case leakage current (I_{IN} , I_{CC} , and I_{OZ}) occur for CMOS at the higher voltage and so the 6.0V values should be used.

AC Electrical Characteristics $v_{CC} = 5V$, $T_A = 25^{\circ}C$, $t_f = t_f = 6$ ns

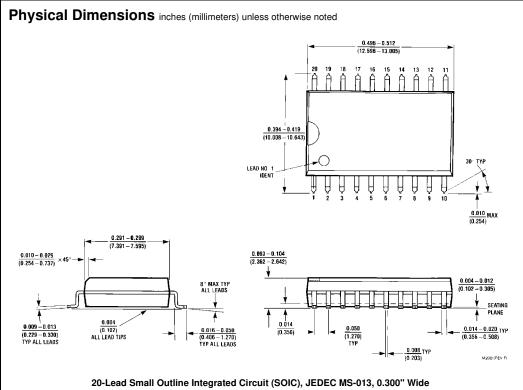
Symbol	Parameter	Conditions	Тур	Guaranteed Limit	Units
t _{PHL} , t _{PLH}	Maximum Propagation	C _L = 45 pF	14	20	ns
	Delay				
t _{PZH} , t _{PZL}	Maximum Enable Delay	$R_L = 1 \text{ k}\Omega$	17	28	ns
	to Active Output	C _L = 45 pF			
t _{PHZ} , t _{PLZ}	Maximum Disable Delay	$R_L = 1 k\Omega$	15	25	ns
	from Active Output	C _L = 5 pF			

AC Electrical Characteristics

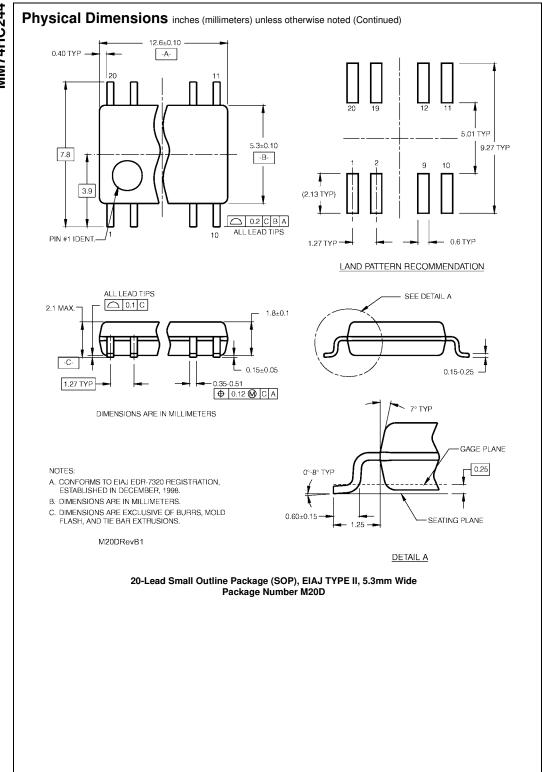
 $V_{CC} = 2.0 V\text{-}6.0 V$, $C_L = 50$ pF, $t_f = t_f = 6$ ns (unless otherwise specified)

Symbol	Parameter	Conditions	v _{cc}	T _A = 25°C		T _A = -40 to 85°C	T _A = -55 to 125°C	Units	
Symbol				Тур		Guaranteed Li	imits	Units	
t _{PHL} , t _{PLH}	Maximum Propagation	C _L = 50 pF	2.0V	58	115	145	171	ns	
	Delay	C _L = 150 pF	2.0V	83	165	208	246	ns	
		C _L = 50 pF	4.5V	14	23	29	34	ns	
		C _L = 150 pF	4.5V	17	33	42	49	ns	
		C _L = 50 pF	6.0V	10	20	25	29	ns	
		C _L = 150 pF	6.0V	14	28	35	42	ns	
t_{PZH}, t_{PZL}	Maximum Output Enable	$R_L = 1 k\Omega$							
	Time	C _L = 50 pF	2.0V	75	150	189	224	ns	
		C _L = 150 pF	2.0V	100	200	252	298	ns	
		C _L = 50 pF	4.5V	15	30	38	45	ns	
		C _L = 150 pF	4.5V	30	40	50	60	ns	
		C _L = 50 pF	6.0V	13	26	32	38	ns	
		C _L = 150 pF	6.0V	17	34	43	51	ns	
t_{PHZ}, t_{PLZ}	Maximum Output Disable	$R_L = 1 k\Omega$	2.0V	75	150	189	224	ns	
	Time	$C_L = 50 pF$	4.5V	15	30	38	45	ns	
			6.0V	13	26	32	38	ns	
t_{TLH} , t_{THL}	Maximum Output		2.0V		60	75	90	ns	
	Rise and Fall Time		4.5V		12	15	18	ns	
			6.0V		10	13	15	ns	
C _{PD}	Power Dissipation	(per buffer)							
	Capacitance (Note 5)	$\overline{G} = V_{IH}$		12				pF	
		$\overline{G} = V_{IL}$		50				pF	
C _{IN}	Maximum Input			5	10	10	10	pF	
	Capacitance								
C _{OUT}	Maximum Output			10	20	20	20	pF	
	Capacitance								

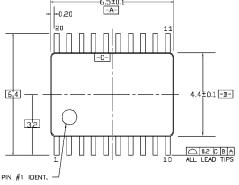
Note 5: C_{PD} determines the no load dynamic power consumption, $P_D = C_{PD} \ V_{CC}^2 f + I_{CC} \ V_{CC}$, and the no load dynamic current consumption, $I_S = C_{PD} \ V_{CC} f + I_{CC}. \label{eq:continuous}$

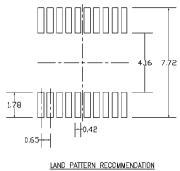


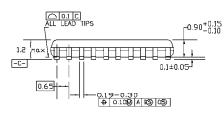
20-Lead Small Outline Integrated Circuit (SOIC), JEDEC MS-013, 0.300" Wide Package Number M20B



Physical Dimensions inches (millimeters) unless otherwise noted (Continued)







DIMENSIONS ARE IN MILLIMETERS

NOTES:

- A. CONFORMS TO JEDEC REGISTRATION MD-153, VARIATION AC, REF NOTE 6, DATE 7/93.
- B. DIMENSIONS ARE IN MILLIMETERS.
- C. DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLDS FLASH, AND TIE BAR EXTRUSIONS.
- D. DIMENSIONS AND TOLERANCES PER ANSI Y14.5M, 1982.

0.09-0.20^J 12.00* R0.09min GAGE PLANE 0.25 SEATING PLANE R0.09min

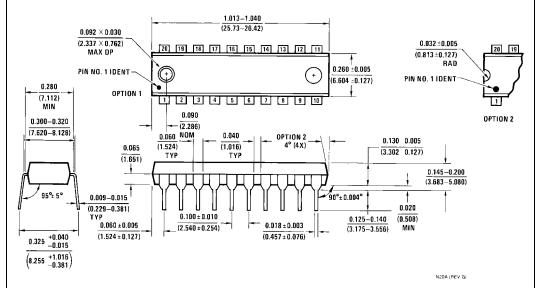
SEE DETAIL A

DETAIL A

MTC20REVD1

20-Lead Thin Shrink Small Outline Package (TSSOP), JEDEC MO-153, 4.4mm Wide Package Number MTC20

Physical Dimensions inches (millimeters) unless otherwise noted (Continued)



20-Lead Plastic Dual-In-Line Package (PDIP), JEDEC MS-001, 0.300" Wide Package Number N20A

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